



PRODUCT CHANGE NOTICE

PCN-2630 REV 1

Notification Date:	Implementation Date:	Product Family:	Change Type:	PCN #:
20 February, 2024	20 May, 2024	Discrete Semiconductors	Additional Wafer Source	2630
TITLE				
Qualification of Additional Wafer Source Using Different Back Metal Composition and Thickness for Select Products				
DESCRIPTION OF CHANGE				
This PCN is being issued to notify customers that in order to assure continuity of supply, Diodes has qualified Diodes internal JK FAB in HsinChu, Taiwan using different back metal composition and thickness at Diodes internal assembly and test site (SAT) and internal "Diodes Technology (Cheng Du) Company Limited" (CAT) for select products listed below. In addition, Diodes has qualified Diodes' foundry Phenitec Semiconductor Corporation 1st FAB in Okayama, Japan as additional wafer source for a select product listed below. Full electrical characterization and high reliability testing has been completed on representative part numbers to ensure there is no change to device functionality or electrical specifications in the datasheet. There will be no change to the Fit or Function of products affected.				
IMPACT				
Continuity of Supply. No change in datasheet electrical parameters and product performance.				
PRODUCTS AFFECTED				
Table 1 – Add JK FAB as additional wafer source using different back metal composition and thickness at SAT Table 2 – Add JK FAB as additional wafer source using different back metal composition and thickness at CAT Table 3 – Add JK FAB as additional wafer source using different back metal composition and thickness at SAT and CAT Table 4 – Add Phenitec 1 st FAB as additional wafer source				
WEB LINKS				
Manufacturer's Notice:	https://www.diodes.com/quality/product-change-notices/diodes-product-change-notices/			
For More Information Contact:	https://www.diodes.com/about/contact-us/contact-sales/			
Data Sheet:	https://www.diodes.com/catalog/			
DISCLAIMER				
Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.				

Table 1 - Add JK FAB as additional wafer source using different back metal composition and thickness at SAT

BZT52C6V2LP-7	BZX84C15-13-F	DDZ4V7BSF-7	DDZ5V6ASF-7	DDZ5V6CSF-7	DDZ6V8ASF-7
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Table 2 - Add JK FAB as additional wafer source using different back metal composition and thickness at CAT

BZT52C10LP-7	DFLT15A-7	DFLT6V5A-7	DFLZ15-7	DFLZ9V1-7	GDZ24LP3-7
BZT52C11LP-7	DFLT16A-7	DFLT7V0A-7	DFLZ16-7	GDZ10LP3-7	GDZ5V1LP3-7
BZT52C20LP-7	DFLT17A-7	DFLT7V5A-7	DFLZ18-7	GDZ11LP3-7	GDZ5V6LP3-7
BZT52C3V6LP-7	DFLT18A-7	DFLT8V5A-7	DFLZ20-7	GDZ12LP3-7	GDZ6V0LP3-7
BZT52C8V2LP-7	DFLT20A-7	DFLT9V0A-7	DFLZ5V6-7	GDZ13LP3-7	GDZ6V2LP3-7
DFLT10A-7	DFLT22A-7	DFLZ10-7	DFLZ6V2-7	GDZ15LP3-7	GDZ6V8LP3-7
DFLT11A-7	DFLT24A-7	DFLZ11-7	DFLZ6V8-7	GDZ18LP3-7	GDZ7V5LP3-7
DFLT12A-7	DFLT5V0A-7	DFLZ12-7	DFLZ7V5-7	GDZ20LP3-7	GDZ8V2LP3-7
DFLT13A-7	DFLT6V0A-7	DFLZ13-7	DFLZ8V2-7	GDZ22LP3-7	GDZ9V1LP3-7
DFLT14A-7					

Table 3 - Add JK FAB as additional wafer source using different back metal composition and thickness at SAT and CAT

BZT52C10LP-7B	BZT52C16LP-7	BZT52C2V7LP-7	BZT52C3V0LP-7	BZT52C4V7LP-7	BZT52C6V8LP-7
BZT52C12LP-7	BZT52C18LP-7	BZT52C36LP-7	BZT52C3V3LP-7	BZT52C5V1LP-7	BZT52C7V5LP-7
BZT52C13LP-7	BZT52C22LP-7	BZT52C36LP-7B	BZT52C3V9LP-7	BZT52C5V6LP-7	BZT52C9V1LP-7
BZT52C13LP-7B	BZT52C24LP-7	BZT52C39LP-7	BZT52C4V3LP-7	BZT52C5V6LP-7B	BZT52C9V1LP-7B
BZT52C15LP-7	BZT52C2V4LP-7	BZT52C39LP-7B			

Table 4 - Add Phenitec 1st FAB as additional wafer source

DDZ36BSF-7					
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